

PER-C39L

Environment Test Report

Report NO: 15I020021

Summary	<p><input checked="" type="checkbox"/> Pass</p> <p><input type="checkbox"/> Fail</p> <p>Note : There is/are ____ defect(s) not list in the report, please check it in the DTS Website.</p> <p><input type="checkbox"/> Pass with Deviation</p> <p>Comment: _____</p>
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Issue date	Approval	Test Engineer
2015-11-30	KJ Wang	Jerry Chen

Test item list

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Testing Result

Num	Test item list	Result	Remark
1	Temperature rise test	Pass	
2	Temperature cycle operation test	Pass	
3	Cold start and hot start test	Pass	

Configuration of EUT

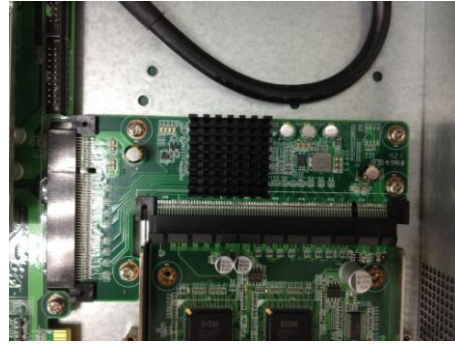
Num	Item	Spec
1.	Test Product: PER-C39L	
	Model Name:	PER-C39L Ver. A0.1
	Board Name:	PER-C39L Ver. A0.1
	LAN Chipset:	Intel 82580EB
2.	Client (Main aid test of system)	
	1. System Name	FWS-7400 Ver. A1.0
	2. Main board	FWB-7400 Ver. A1.0
	3. BIOS Ver.	FWS-7400 R1.5 (K741AM15) (06/12/2015)
	4. CPU Type	Intel Core i3-4360 3.7GHz x 4
	5. Chipset	Intel H81
	6. LAN Module	PER-C39L Ver. A0.1 x 1 (LAN Chipset – Intel 82580EB)
	7. RISER	PER-T356 Ver. A0.2
	8. Memory	DSL DDR3 1333 4GB CL9 (ELPID / J2108BCSE - DJ – F) x 1
	9. 2.5” SATA HDD	Toshiba / MQ01ABD032 320GB
	10. Test Software	ubuntu 14.10 / Run iPerf test
	11. Power supply	FSP / FSP250-50LC
3.	Server (Secondary aid test of system)	
	1. System Name	FWS-7811 Ver. A1.0
	2. Main board	FWB-7400 Ver. A1.0
	3. BIOS Ver.	FWS-7400 R1.5 (K741AM15) (06/12/2015)
	4. CPU Type	Intel Core i3-4360 3.7GHz x 4
	5. Chipset	Intel H81
	6. LAN Module	PER-C39L Ver. A0.1 x 1 (LAN Chipset – Intel 82580EB)
	7. RISER	PER-T356 Ver. A0.2
	8. Memory	Transcend DDR3 1333 U 4GB (SEC 231 HCKO K4B2G0846D) x 1
	9. 2.5” SATA HDD	Toshiba / MQ01ABD032 320GB
	10. Test Software	ubuntu 14.10 / Run iPerf test
	11. Power Supply	Zippy / R1V2-5275V4H

Photos

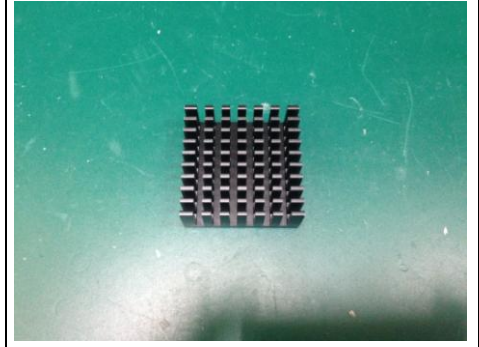
LAN Module - PER-C39L



Riser Module - PER-T356



Chipset Heat Sink



Temperature rise test

Test Date: 11-26 ~ 27-2015

Test Product: PER-C39L with PER-T356 and FWS-7400

Test Site: AAEON QE Dept.

Test Standard: Refer to EN 61131-2(94), UL508 (94)

Temperature Measurement:

40 Channel Thermal Recorder:

YOKOGAWA Inc,

Model: DA100-13-1D

Date of Calibration: 09/10/2015

Serial Number: 12A323190

Test Condition:

Ambient temperature: 40°C

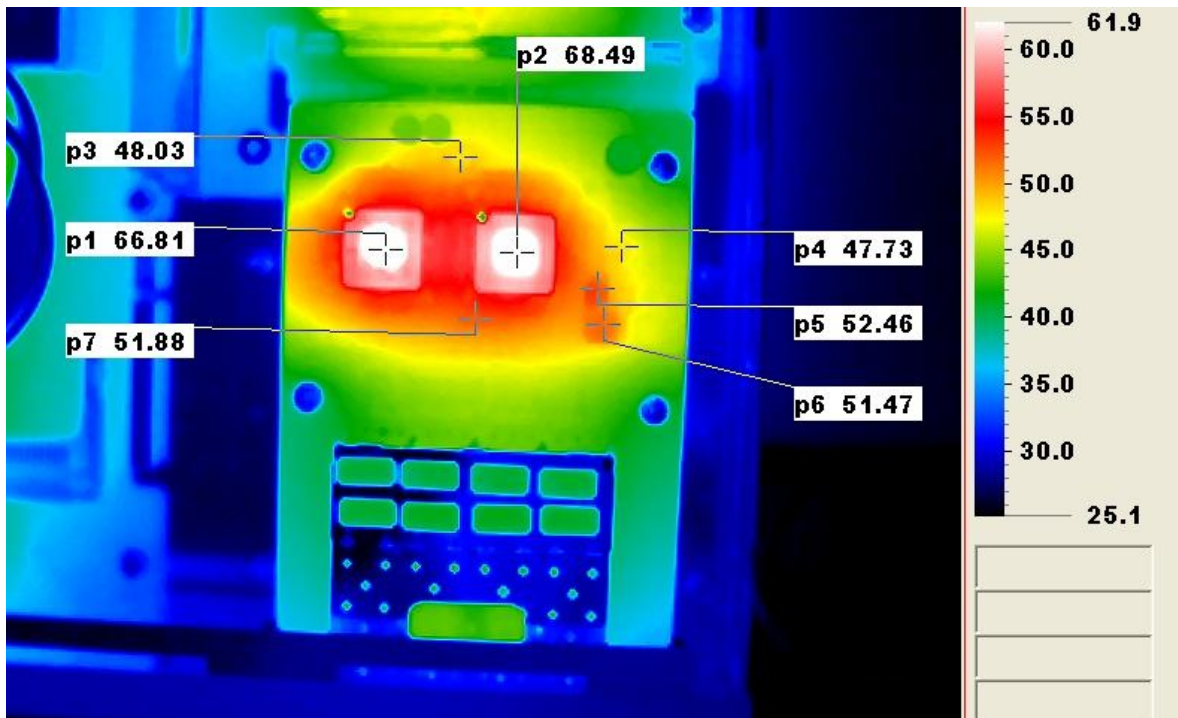
Continuous running till thermal stable (within less than 1°C)

Test Software:

ubuntu 14.10 / Run iPerf test

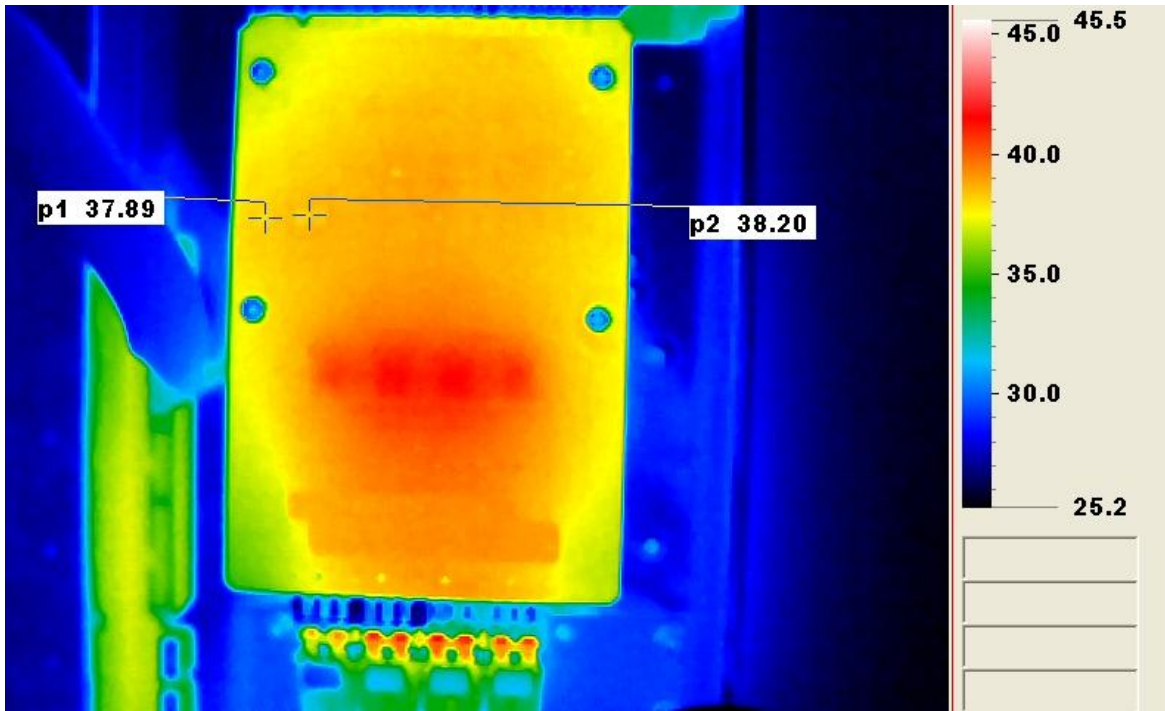
Terminal Recorder:

Front Side:



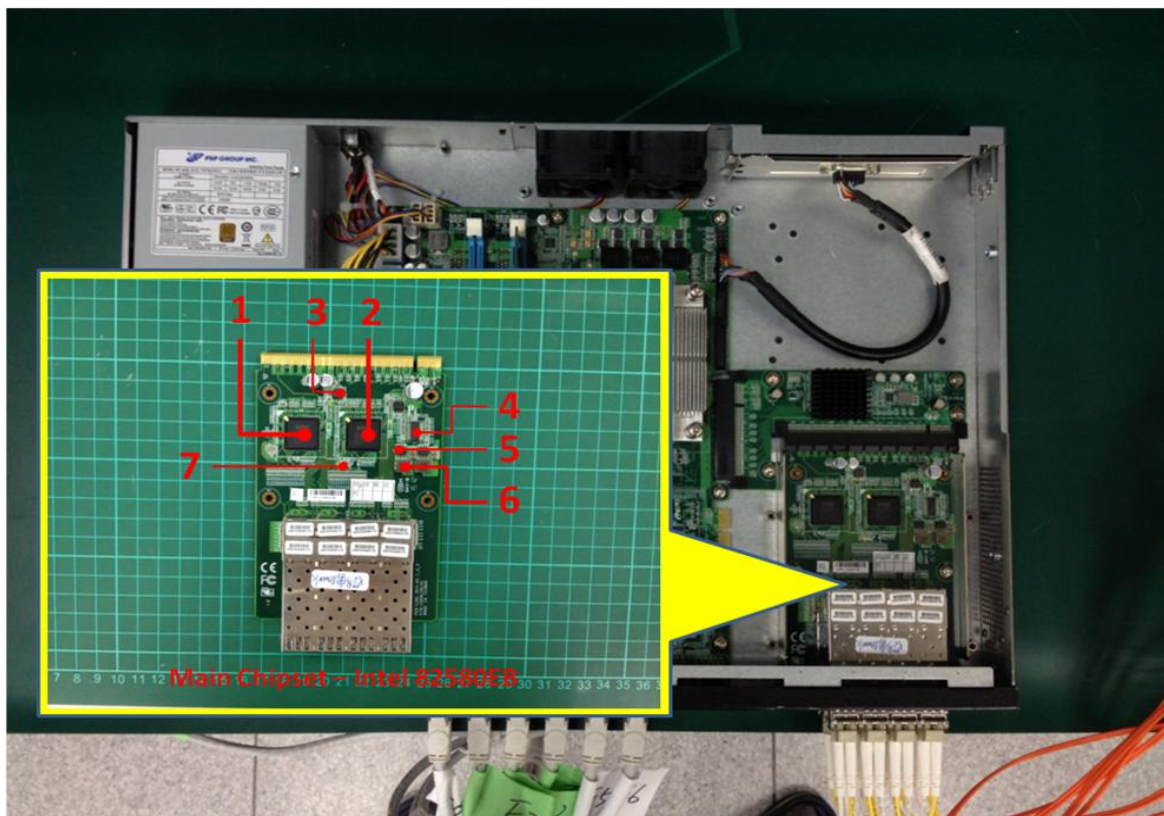
Temperature rise test

Rear Side:



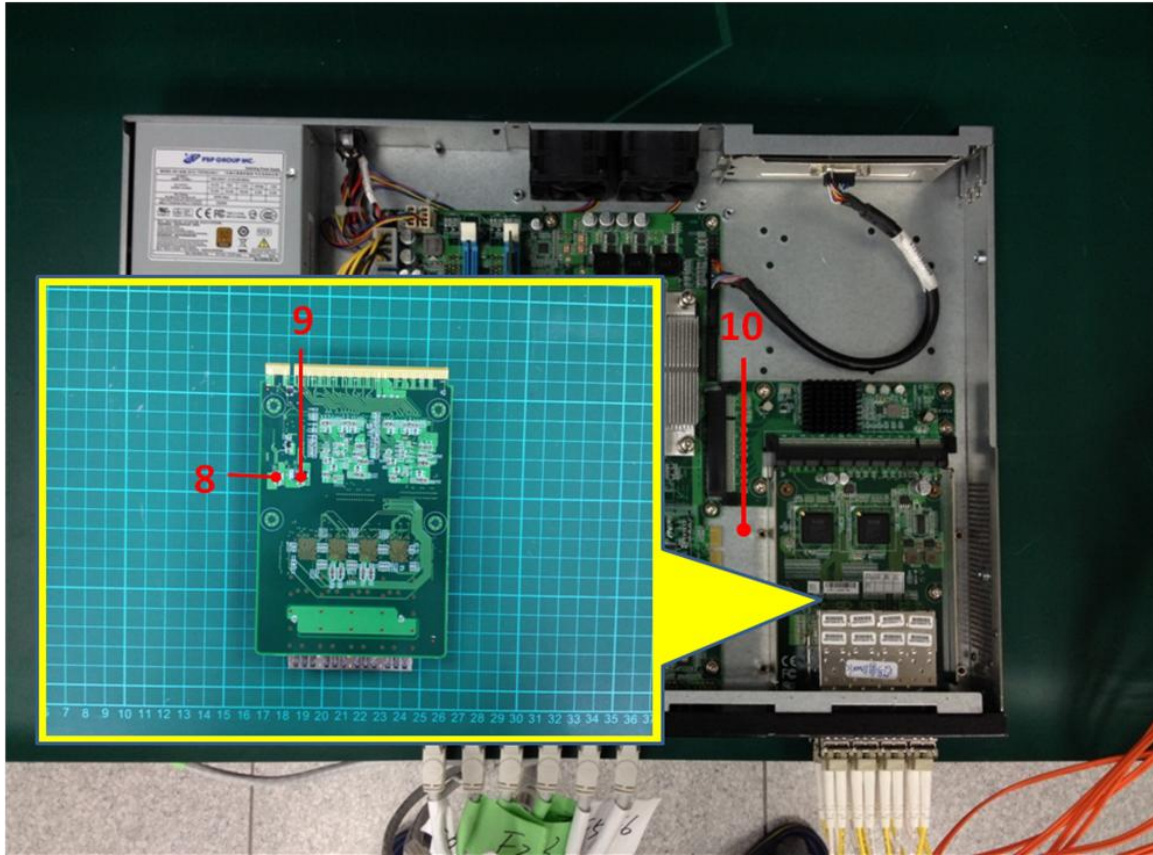
Measuring Thermal Couple Position :

Front Side:



Temperature rise test

Rear Side:



Temperature rise test

Thermal profile data:

PER-C39L with PER-T356 and FWS-7400

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				40°C	25°C		
1	U11	IC.PCI-E.GbE Controller Quad Port.PBGA 256P.Intel.82580EB	100	55.1	40.1		
2	U12	IC.PCI-E.GbE Controller Quad Port.PBGA 256P.Intel.82580EB	100	56.4	41.4		
3	U14	IC.Serier SPI BUS EEPROM.SO8.256Kbit.ST.M95256-WMN6P	100	52.8	37.8		
4	U13	IC.PWM Controller.SSOP 28P.INTERMIL.ISL6227CAZ	100	48.8	33.8		
5	Q22	PWR.SOP-8.Dual.MOSFET.Sinopower.APM7334KC-TRG	125	51.7	36.7		
6	L34	COIL.3.3uH.DCR=28m ohm.GOTREND.GSTC063P-3R3MN	140	51.6	36.6		
7	Y2	X'TAL.25MHz.4P.20PF.30ppm.ECERA.FL2500039	100	51.5	36.5		
8	C239	CAP.100uF.6.3V.40mOhm.KEMET.T520B107M006ATE040	120	47.1	32.1		
9	C240	TCC.220uF.10V.D.VISHAY.293D227X9010D2TE3	140	48	33		
10	N/A	Control Box Inside Air Temperature	N/A	40.5	25.5		
11	N/A	Control Box External Surface Temperature	N/A	39.4	24.4		
12	N/A	Chamber Air Temperature	N/A	40	25		

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
 - "TAT" indicates the actual measured temperature under product specification.
 - "TPT" indicates the predicted temperature under 25°C working environmental.
 - "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- 5. Judgment Criteria:**
- **Fail** : Tm > Tc; The measured value is over specification plus margin.
 - **Margin** : Tc > Tm > Tc-5°C; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : Tm < Tc-5°C; The measured value is with safety margin.

4. Defect NO.

Temperature cycle test

Test Date: 11-23 ~ 25-2015

Test Product: PER-C39L with PER-T356 and FWS-7400

Test Site: AAEON QE Dept.

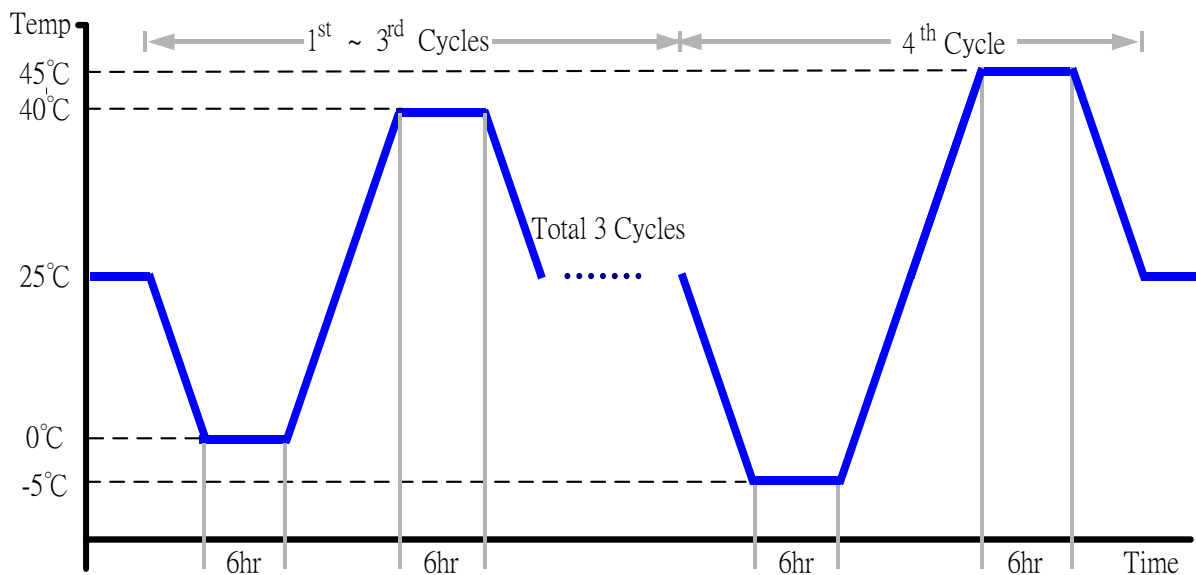
Test Standard: Refer to IEC68-2-14 Testing procedures
Test N: Change of temperature Test

Test Equipment:

Programmable Temperature & Humidity Chamber: (K.SON. INS. TECH. CORP.)
Model: THS-D4H + - 100
Date of Calibration: 11/13/2015
Serial Number: 2582

Test Condition:

1. Test Low Temperature: 0°C (1~3 cycles)
-5°C (4th cycle)
2. Test High Temperature: 40°C (1~3 cycles)
45°C (4th cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2°C/min
5. Test cycle: 4 cycles
6. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (PER-C39L)

Test Result:

No issues were found during the temperature operation cycle test.

Cold start and hot start test

Test Date: 11-25 ~ 26-2015

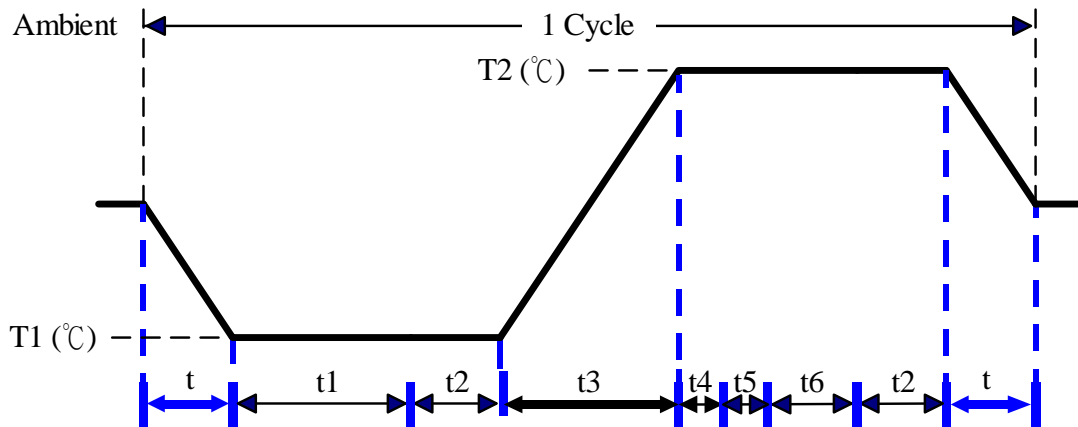
Test Product: PER-C39L with PER-T356 and FWS-7400

Test Site: AAEON QE Dept.

Test Standard: Refer to IEC 68-2-14 Testing procedures
Test N: Change of temperature Test

Test Equipment:
Programmable Temperature & Humidity Chamber: (K.SON. INS. TECH. CORP.)
Model: THS-D4H + - 100
Date of Calibration: 11/13/2015
Serial Number: 2582

Test Condition:



Parameters	Description
T1	-5°C
T2	45°C
t1	4 hrs
t2, t6	2 hrs
t4, t5	1hrs
t, t3	2°C/min
n (Cycle)	1

t = temprature slope
t , t1, t6: Power Off
t2: Power on/off test 10 times (on 2 min / off 5min)
t3, t4: Run iPerf test
t5: ubuntu 14.10 Software restart test 3 times
Test Software: ubuntu 14.10

Test Result:

- a. No issues were found during the cold start test.
- b. No issues were found during the hot start test.